

L Number	Hits	Search Text	DB	Time stamp
-	1223	(surfactant\$1 surface adj active) same molecular adj weight and polish\$3	USPAT; US-PGPUB; EPO; JPO	2004/03/19 13:01
-	425	((surfactant\$1 surface adj active) same molecular adj weight and polish\$3) and polish\$3 same (metal\$3 copper cu)	USPAT; US-PGPUB;	2004/03/19 13:03
-	96	((surfactant\$1 surface adj active) same molecular adj weight and polish\$3) and polish\$3 same (metal\$3 copper cu)) and (surfactant\$1 surface adj active) near15 molecular adj weight	EPO; JPO USPAT; US-PGPUB;	2004/03/19 13:02
-	96	((surfactant\$1 surface adj active) same molecular adj weight and polish\$3) and polish\$3 same (metal\$3 copper cu)) and (surfactant\$1 surface adj active) near15 molecular adj weight) and (surfactant\$1 surface adj active) near15 molecular adj weight	EPO; JPO USPAT; US-PGPUB;	2004/03/19 13:02
-	49	((surfactant\$1 surface adj active) same molecular adj weight and polish\$3) and polish\$3 same (metal\$3 copper cu)) and (surfactant\$1 surface adj active) near15 molecular adj weight) and (surfactant\$1 surface adj active) near15 molecular adj weight) and polish\$3 near15 (slurr\$3 paste\$1 composition\$1 mixture\$1)	EPO; JPO USPAT; US-PGPUB;	2004/03/19 13:04